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6-29-01
Molles

Docket No.: 202009US-2 DIV

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

Shigenobu MAEDA

: EXAMINER:

SERIAL NO: NEW APPLICATION

FILED: HEREWITH

: GROUP ART UNIT:

FOR: MANUFACTURING METHOD OF
SEMICONDUCTOR WAFER,
SEMICONDUCTOR MANUFACTURING
APPARATUS, AND SEMICONDUCTOR
DEVICE

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Prior to examination on the merits, please amend the above-identified patent
application as follows:

IN THE CLAIMS

✓
Please cancel without prejudice or disclaimer Claims 1-20.

Please add Claims 21-24 as follows:

sub B₁₇--21. A method of manufacturing a semiconductor device for building a circuit composed
of combined plural circuit elements into a semiconductor chip, comprising:

A1
expressing a layout pattern of said circuit by using mask patterns respectively prepared
for said plural circuit elements.

22. ~~The~~ method of manufacturing a semiconductor device according to Claim 21,
wherein